

LB11867FV

Variable Speed Single-phase Full-wave Pre-driver for Fan Motor

Monolithic Digital IC

Overview

LB11867FV is a single-phase bipolar driving motor pre-driver with the variable speed function compatible with external PWM signal. With a few external parts, a highly-efficient and highly-silent variable drive fan motor with low power consumption can be achieved. This product is best suited for driving of the server requiring large air flow and large current and the fan motor of consumer appliances.

Features

- Single-phase Full-wave Driving Pre-driver
 - ⇒ Low-saturation Drive Using External PMOS–NMOS Enables High-efficiency Low Power-consumption Drive
- Variable Speed Control Possible with External PWM Input
 - ⇒ Separately-excited Upper Direct PWM ($f = 30$ kHz) Control Method Ensures Highly Silent Speed Control
- Current Limiting Circuit Incorporated
 - ⇒ Chopper Type Current Limiting Made at Startup and during Lock
- Reactive Current Cut Circuit Incorporated
 - ⇒ Reactive Current before Phase Changeover is Cut, Ensuring Highly Silent and Low Power-consumption Drive
- Minimum Speed Setting Pin
 - ⇒ Minimum Speed can be Set by Setting the Resistance
- Soft Start Setting Pin
- Lock Protection and Automatic Reset Circuits Incorporated
- FG (Rotation Speed Detection) Output
- Thermal Shutdown Circuit Incorporated

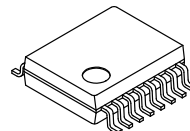
Typical Applications

- Computing & Peripherals
- Industrial
- Server
- Vending Machine



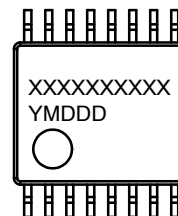
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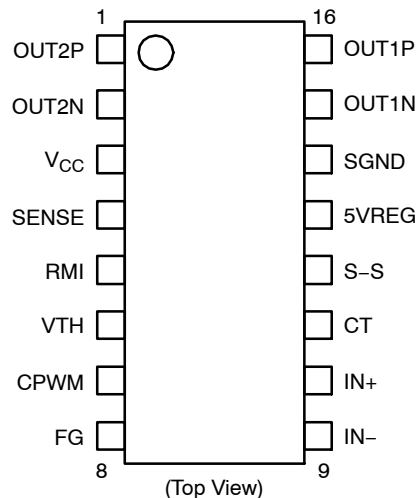
SSOP16
CASE 565AM

MARKING DIAGRAM



XXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

PIN ASSIGNMENT



ORDERING INFORMATION

See detailed ordering and shipping information on page 9 of this data sheet.

SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

Symbol	Parameter	Conditions	Ratings	Unit
V_{CC} max	V_{CC} Pin Maximum Supply Voltage		18	V
IOUTN max	OUTN Pin Maximum Output Current		20	mA
IOUTP max	OUTP Pin Maximum Sink Current		20	mA
VOUT max	OUT Pin Output Withstand Voltage		18	V
VVTH, VRMI max	VTH, RMI Pins Withstand Voltage		7	V
V_{S-S} max	S-S Pin Withstand Voltage		7	V
V_{FG} max	FG Output Pin Withstand Voltage		19	V
I_{FG} max	FG Pin Maximum Output Current		10	mA
I_{5VREG} max	5VREG Pin Maximum Output Current		20	mA
P_d max	Allowable Power Dissipation	With specified substrate (Note 1)	800	mW
T_{opr}	Operating Temperature	(Note 2)	-30 to 95	$^\circ\text{C}$
T_{stg}	Storage Temperature		-55 to 150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Specified substrate: 114.3 mm $\times$ 76.1 mm $\times$ 1.6 mm, glass epoxy board.
2. T_j max = 150°C must not be exceeded.

RECOMMENDED OPERATING CONDITIONS ($T_A = 25^\circ\text{C}$)

Symbol	Parameter	Conditions	Ratings	Unit
V_{CC}	V_{CC} Supply Voltage		5.5 to 16	V
VTH, RMI	VTH, RMI Input Voltage Range		0 to 5	V
VICM	Hall Input Common-phase Input Voltage Range		0.2 to 3	V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, $V_{CC} = 12\text{ V}$)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CC1}	Circuit Current	During drive	5.5	7.5	9.5	mA
I_{CC2}		During lock protection	5.5	7.5	9.5	mA
5VREG	5VREG Voltage	$I_{5VREG} = 5\text{ mA}$	4.80	4.95	5.10	V
VLIM	Current Limiting Voltage		185	200	215	mV
V_{CPWMH}	CPWM Pin "H" Level Voltage		2.8	3.0	3.2	V
V_{CPWML}	CPWM Pin "L" Level Voltage		0.9	1.1	1.3	V
I_{CPWM1}	CPWM Pin Charge Current	$V_{CPWM} = 0.5\text{ V}$	24	30	36	μA
I_{CPWM2}	CPWM Pin Discharge Current	$V_{CPWM} = 3.5\text{ V}$	21	27	33	μA
FPWM	CPWM Oscillation Frequency	$C = 220\text{ pF}$	–	30	–	kHz
V_{CTH}	CT Pin "H" Level Voltage		2.8	3.0	3.2	V
V_{CTL}	CT Pin "L" Level Voltage		0.9	1.1	1.3	V
I_{CT1}	CT Pin Charge Current	$V_{CT} = 0.5\text{ V}$	1.6	2.0	2.5	μA
I_{CT2}	CT Pin Discharge Current	$V_{CT} = 3.5\text{ V}$	0.16	0.20	0.25	μA
R_{CT}	CT Pin Charge/Discharge Ratio	I_{CT1}/I_{CT2}	8	10	12	times
I_{S-S}	S-S Pin Discharge Current	$V_{S-S} = 1\text{ V}$	0.4	0.5	0.6	μA

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, $V_{CC} = 12\text{ V}$) (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{ONH}	OUTN Output H-level Voltage	$I_O = 10\text{ mA}$	–	$V_{CC}-0.85$	$V_{CC}-1.00$	V
V_{ONL}	OUTN Output L-level Voltage	$I_O = 10\text{ mA}$	–	0.9	1.00	V
V_{OPL}	OUTP Output L-level Voltage	$I_O = 10\text{ mA}$	–	0.5	0.65	V
VHN	Hall Input Sensitivity	IN^+ , IN^- differential voltage (including offset and hysteresis)	–	± 10	± 20	mV
V_{FGL}	FG Output L-level Voltage	$I_{FG} = 5\text{ mA}$	–	0.15	0.30	V
I_{FGL}	FG Pin Leakage Current	$V_{FG} = 19\text{ V}$	–	–	20	μA
IVTH/IRMI	VTH/RMI Pin Bias Current	CPWM = VTH/RMI = 2 V	–	–	0.1	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

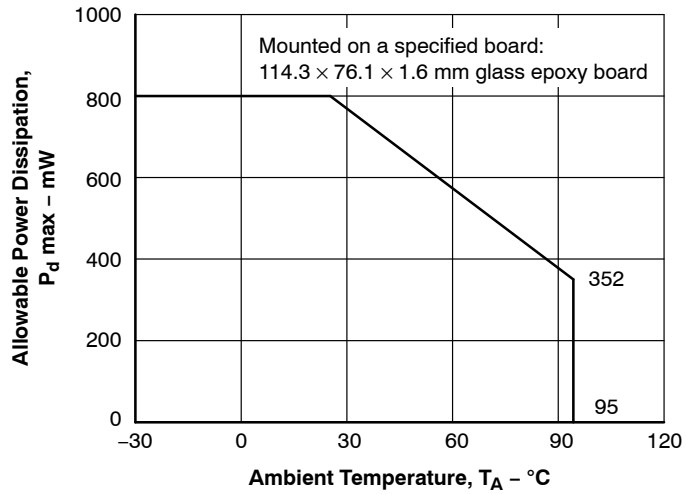


Figure 1. $P_d \text{ max} - T_A$

LB11867FV

BLOCK DIAGRAM

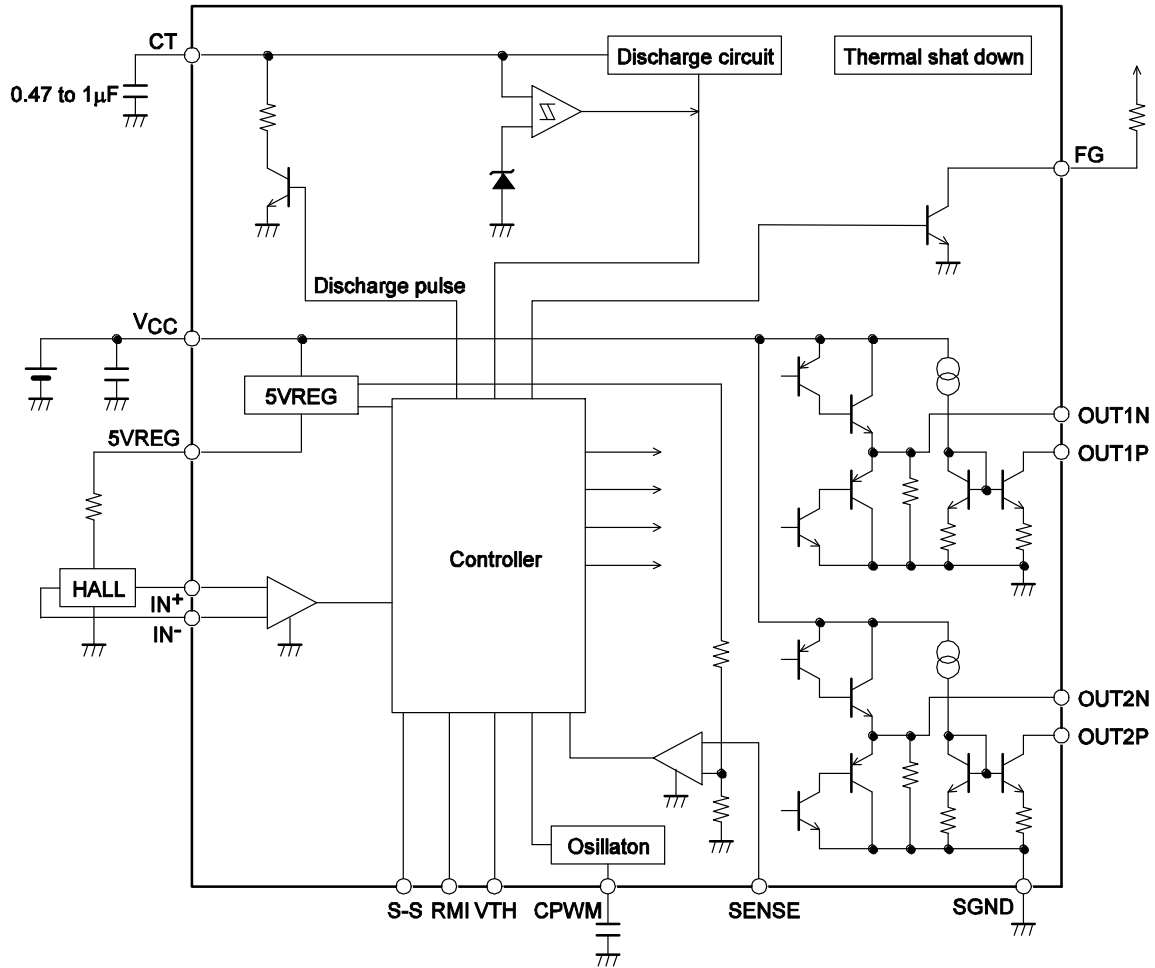


Figure 2. Block Diagram

TRUTH TABLE - DRIVE LOCK CPWM = H VTH, RMI, S-S = L

IN-	IN+	CT	OUT1P	OUT1N	OUT2P	OUT2N	FG	Mode
H	L	L	L	L	OFF	H	L	OUT1 → 2 drive
L	H		OFF	H	L	L	OFF	OUT2 → 1 drive
H	L	H	OFF	L	OFF	H	L	Lock protection
L	H		OFF	H	OFF	L	OFF	

TRUTH TABLE - SPEED CONTROL CT, S-S = L

VTH, RMI	CPWM	IN-	IN+	OUT1P	OUT1N	OUT2P	OUT2N	Mode
L	H	H	L	L	L	OFF	H	OUT1 → 2 drive
		L	H	OFF	H	L	L	OUT2 → 1 drive
H	L	H	L	OFF	L	OFF	H	Regeneration mode
		L	H	OFF	H	OFF	L	

NOTE: For VTH, RMI, and S-S pins, refer to the timing chart.

***7: VTH Pin**

Speed control pin.

Connect this pin to GND when it is not used (at full speed).

For the control method, refer to the timing chart.

For control with pulse input, insert the current limiting resistor and use the pin with the frequency of 20 kHz to 100 kHz (20 kHz to 50 kHz recommended).

***8: SENSE Pin**

Current limiting detection pin.

When the pin voltage exceeds 0.2 V, the current is limited and the operation enters the lower regeneration mode.

Connect this pin to GND when it is not to be used.

***9: FG Pin**

Rotation speed detection pin.

This is an open collector output, which can detect the rotation speed from the FG output according to the phase changeover. Keep this pin open when it is not to be used.

***10: CT Pin**

Pin to connect the lock detection capacitor.

The constant-current charge and discharge circuits incorporated cause locking when the pin voltage becomes 3.0 V and unlocking when it is 1.1 V.

Connect the pin to GND when it is not to be used (locking not necessary).

***11: S-S Pin**

Pin to connect the soft-start setting capacitor.

Connect the capacitor between 5VREG and S-S pin.

This pin enables setting of the soft start time according to the capacity of the capacitor.

See the timing char.

Connect the pin to GND when it is not to be used.

CONTROL TIMING CHART (SPEED CONTROL)

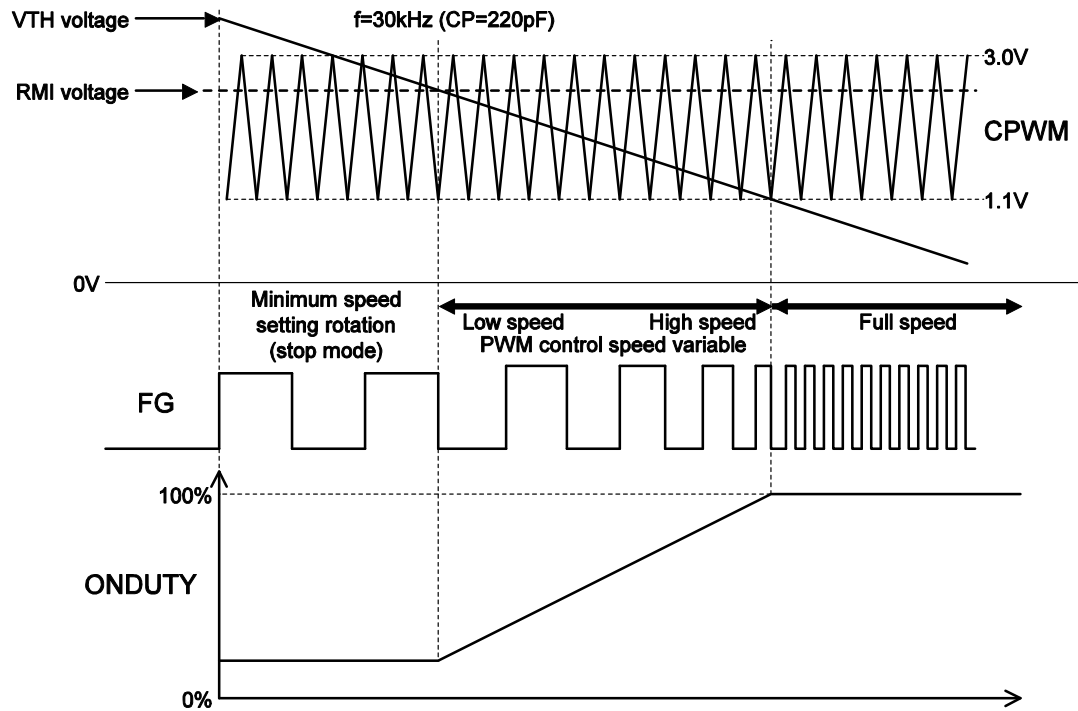


Figure 4. Control Timing Chart – Speed Control

1. Minimum Speed Setting (Stop) Mode
The low-speed fan rotation occurs at the minimum speed set with the RMI pin. When the minimum speed is not set (RMI pin pulled up to 5VREG), the motor stops.
2. Low Speed $\leftrightarrow$ High Speed
PMW control is made by comparing the CPWM oscillation voltage (1.1 V $\leftrightarrow$ 3.0 V) and VTH voltage.
Both upper and lower output TRs are turned ON when the VTH voltage is low. The upper output

TR is turned OFF when the VTH voltage is high, regenerating the coil current in the lower TR. Therefore, as the VTH voltage decreases, the output ON-DUTY increases, causing increase in the coil current, raising the motor rotation speed. The rotation speed can be monitored with the FG output.

3. Full Speed Mode
The full speed mode becomes effective when the VTH voltage is 1.1 V or less. (Set VTH = GND when the speed control is not to be made)

CONTROL TIMING CHART (SOFT START)

1. At $V_{TH} < RMI$ Voltage

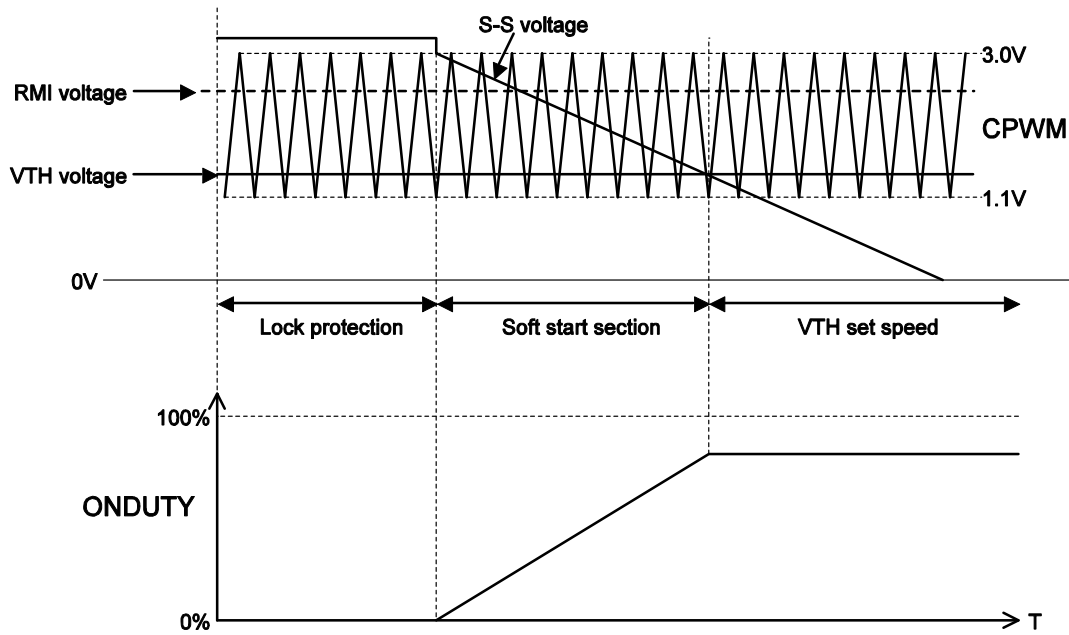


Figure 5. At $V_{TH} < RMI$ Voltage

2. At $V_{TH} > RMI$ Voltage

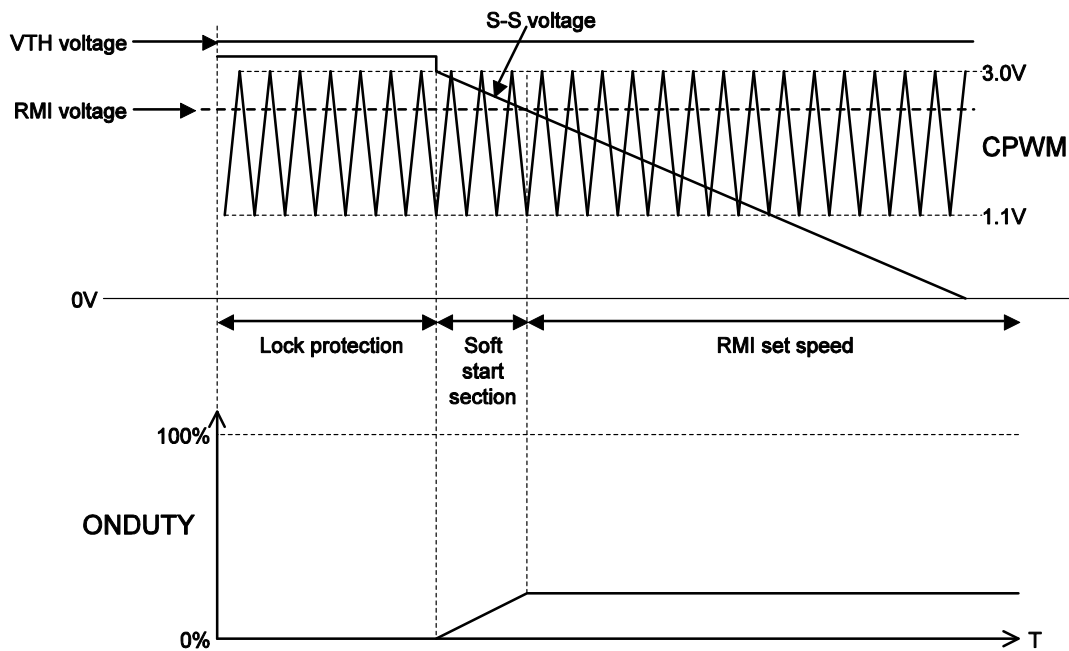


Figure 6. At $V_{TH} > RMI$ Voltage

Adjust the S-S pin voltage gradient by means of the capacitance of the capacitor between the S-S pin and 5VREG.
Recommended capacitor: 0.1 μF to 1 μF

LB11867FV

ORDERING INFORMATION

Device	Package	Wire Bond	Shipping [†] (Qty / Packing)
LB11867FV-MPB-E	SSOP16 (225mil) (Pb-Free)	Au-wire	90 / Fan-Fold
LB11867FV-MPB-H	SSOP16 (225mil) (Pb-Free / Halogen Free)	Au-wire	90 / Fan-Fold
LB11867FV-TLM-E	SSOP16 (225mil) (Pb-Free)	Au-wire	2,000 / Tape & Reel
LB11867FV-TLM-H	SSOP16 (225mil) (Pb-Free / Halogen Free)	Au-wire	2,000 / Tape & Reel
LB11867FV-W-AH	SSOP16 (225mil) (Pb-Free / Halogen Free)	Cu-wire	2,000 / Tape & Reel

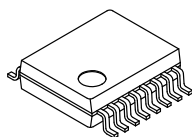
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

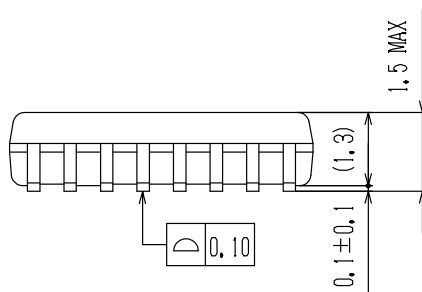
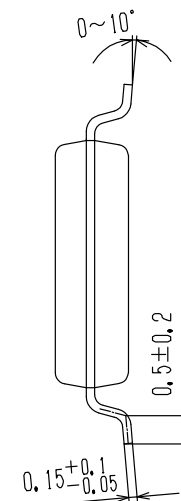
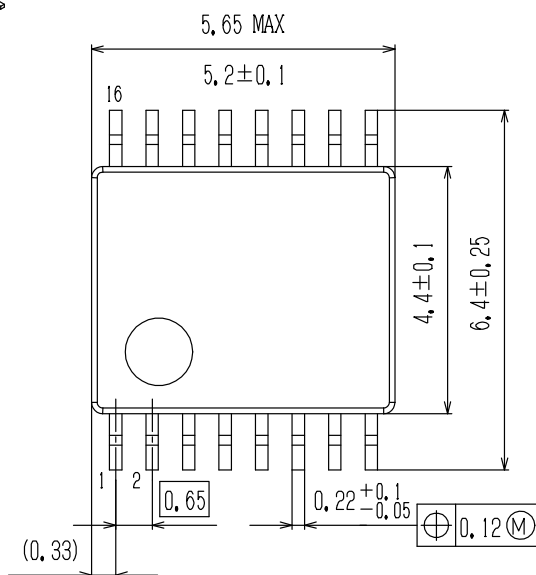
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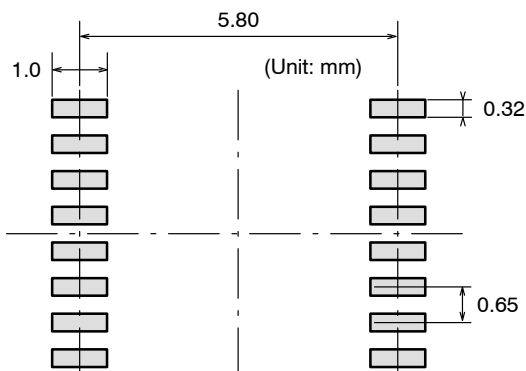


SSOP16 (225mil)
CASE 565AM
ISSUE A

DATE 23 OCT 2013



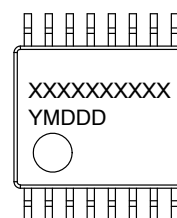
SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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DESCRIPTION:	SSOP16 (225MIL)	PAGE 1 OF 1

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